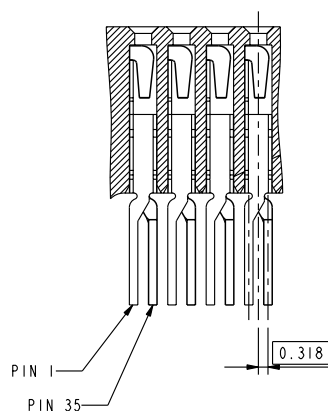


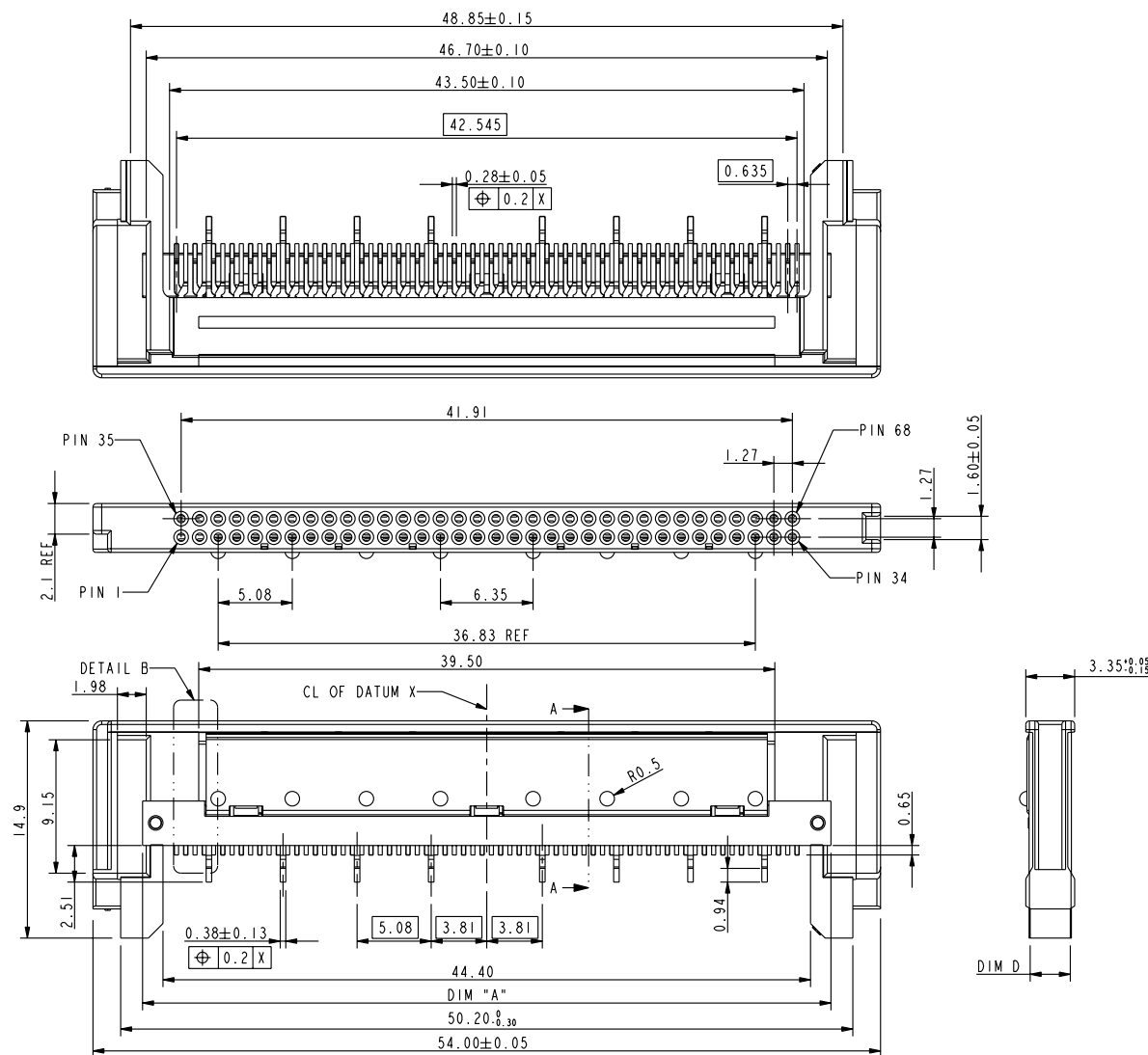


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DETAIL B
SCALE 4.0



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ENVIRONMENT

mat'l code				tolerances unless otherwise specified				CUSTOMER				www.fciconnect.com	
ltr	ecn no.	dr	date	linear	.X±0.3		projection 	title 68P CARDBUS RECEPTACLE ASS'Y	product family PCMCIA	code	size	dwg no 10014747	sheet 1 of 2
H	DG06-0003	Kason	01/04/'06		.XX±0.13								
J	DG06-0120	C S	03/20/'06		.XXX±0.05								
K	DG06-0350	P M	08/21/'06	angles	0°±2°		MM scale 1.000						
L	DG07-0045	C S	30/01/'07	dr	KENNY TAI	10/03/'02							
M	DG08-0116	NZ	05/27/'08	enrg	KENNY TAI	10/03/'02							
				chr	KENNY TAI	10/03/'02							
G	T05-0079	TAI	04/12/'05	appd	PAUL WANG	10/03/'02							
sheet index		revision		M	M								
		sheet		I	2								

form no. 7530-001-103

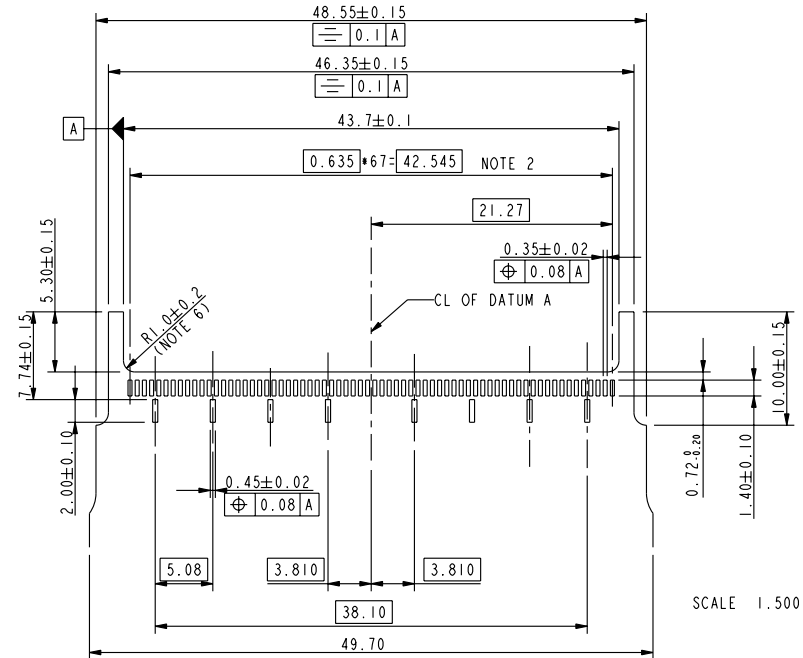
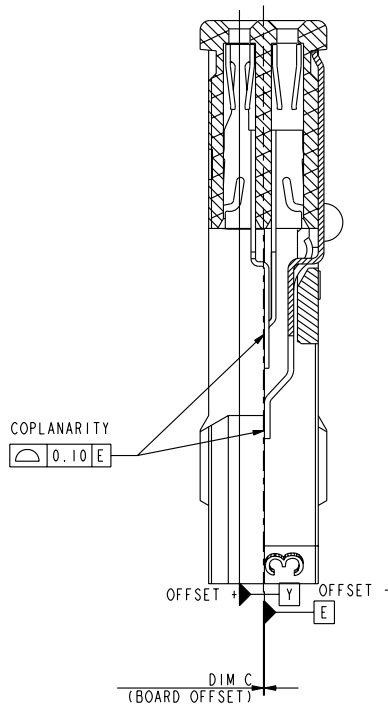
PDM: Rev:M

STATUS:Released

Printed: Jun 07, 2008



PRODUCT NUMBER	DIM A	BOARD OFFSET DIM C	DIM D	PACKING
10014747-001	47.20±0.10	0	2.85±0.05	SEE NOTE 4 FOR DETAIL DESCRIPTION
10014747-002	47.20±0.10	0.3	2.85±0.05	
10014747-003	47.20±0.10	0.6	2.85±0.05	
10014747-004	46.70±0.10	0	2.85±0.05	
10014747-006	46.70±0.10	0	2.75±0.05	
10014747-007	47.20±0.10	-0.3	2.85±0.05	
10014747-XXXLF	47.20±0.10 (-001~-003,005) 46.70±0.10 (-004,-006)	(LEAD FREE PLATING, SEE NOTE 7)		
10014747-XXXLF	47.20±0.10 (-001~-003,005) 46.70±0.10 (-004,-006)	(LEAD FREE PLATING, SEE NOTE 7)		



- NOTE:
- MATERIAL:
CONTACT: PHBR 0.12±
GROUND SHIELD: BRASS 0.15±
HOUSING: LCP UL 94V-0, BLACK
 - FINISH:
CONTACT: ALL OVER --- Ni UNDER 0.5 MICRON; CONTACT --- Au or GXT PLATING 0.38 MICRON: Δ
SOLDER TAIL --- TIN LEAD 2.5 MICRON.
GROUND SHIELD: ALL OVER --- Ni UNDER 1.27 MICRON; CONTACT --- Au or GXT PLATING 0.38 MICRON: Δ
SOLDER TAIL --- TIN LEAD 3.8 MICRON.
 - MAX. BOW OF PCB ON THIS DIMENSION IS 0.1mm.
 - MATED CONNECTOR SHOULD BE BASED ON JEIDA AND PCMCIA SPECIFICATION.
 - PACKING DETAIL: (REFER TO GS-14-723 AND GS-14-920)
-XXX USE TRAY PACKAGE 1872 PCS / CARTON.
-XXXT USE TAPE AND REEL 750 PCS / REEL.
-XXXS USE TRAY PACKAGE 200 PCS / CARTON.
-XXXX USE TAPE AND REEL 600 PCS / REEL.
 - ELIMINATE THE CORNER TO PREVENT INTERFERENCE WITH SOLDER TAIL.
 - LEAD FREE PLATING:
FOR CONTACT TAIL: Ni UNDER PLATING 0.5 MICRON, TIN 2.5 MICRON;
FOR GROUND SHIELD TAIL: Ni UNDER PLATING 1.27 MICRON, TIN 3.8 MICRON.
 - PRODUCT SPEC. REFER TO GS-12-228.
 - 10014747-XXXLF PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
 - THE HOUSING WILL WITHSTAND EXPOSURE TO 280°C PEAK TEMPERATURE FOR 10 SECONDS IN IR-REFLOW

RECOMMENDED PCB LAYOUT

mat'l code				tolerances unless otherwise specified		CUSTOMER	
ltr	ecn no.	dr	date	linear	.X±0.3	projection	COPY
M					.XX±0.13		
					.XXX±0.05		
				angles	0°±2°	MM	scale
				dr	KENNY TAI 10/03/'02		
				enrg	KENNY TAI 10/03/'02		
				chr	KENNY TAI 10/03/'02	1.000	A
				appd	PAUL WANG 10/03/'02		
sheet index	revision sheet						

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